



SOT1288-2

Plastic single-ended multi-chip package; 6 interconnections;
3 in-line leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SIP3
Package type industry code	SIP3
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	5-8-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.9	-	4	4.1	mm
E	package width		5.25	-	5.35	5.45	mm
e	nominal pitch		-	-	2.54	-	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

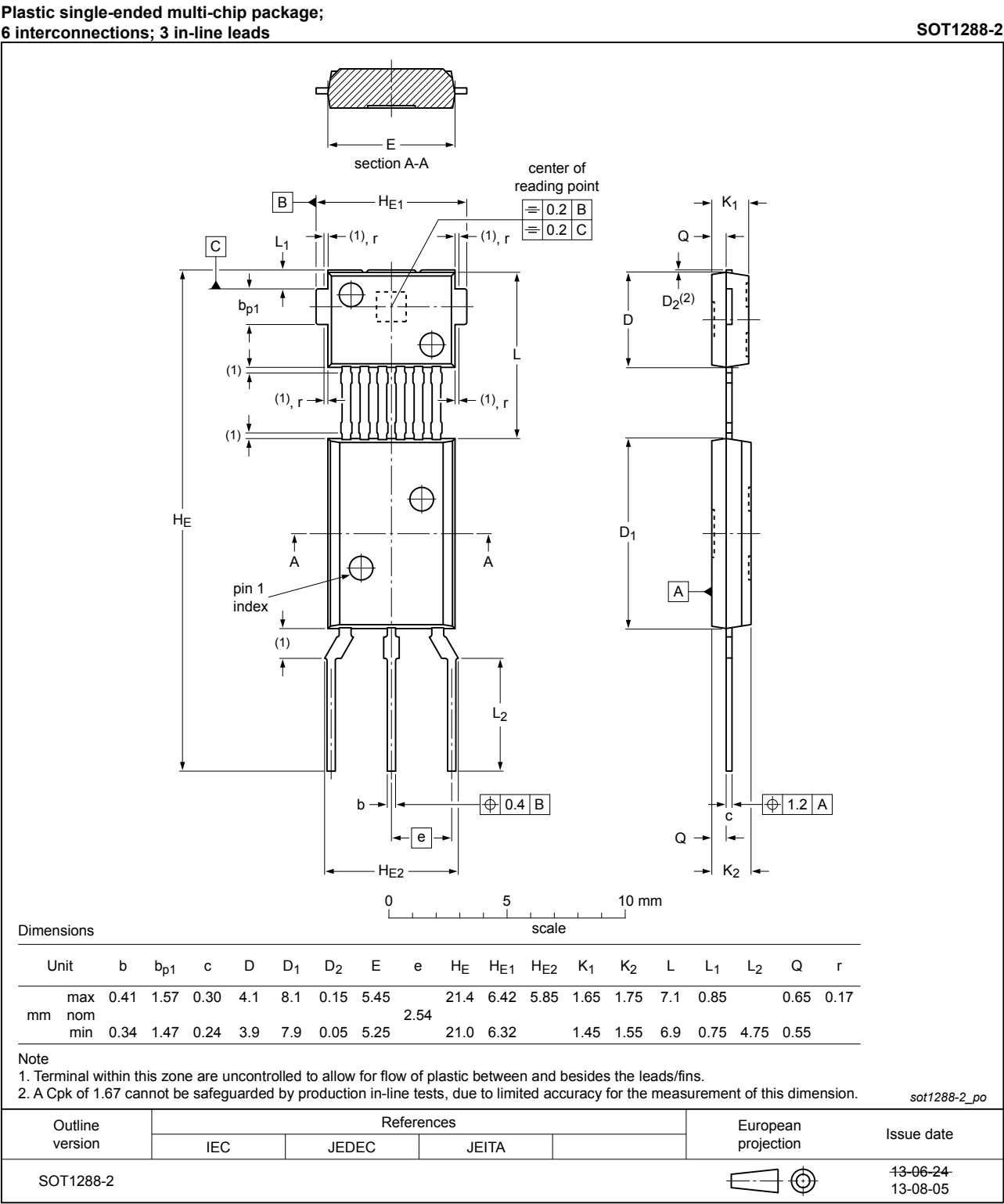


Fig. 1. Package outline SIP3 (SOT1288-2)

3. Legal information

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